PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT4518833

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
JONATHAN E. BUCK	07/21/2017
JOHN A. MONGOLD	07/24/2017

RECEIVING PARTY DATA

Name:	Samtec, Inc.
Street Address:	520 Park East Boulevard
City:	New Albany
State/Country:	INDIANA
Postal Code:	47151-1147

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	29611655

CORRESPONDENCE DATA

Fax Number: (571)313-7421

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 571-313-7440

Email: mrhodes@kbiplaw.com Correspondent Name: **KEATING & BENNETT LLP** Address Line 1: 1800 ALEXANDER BELL DR.

Address Line 2: SUITE 200

Address Line 4: RESTON, VIRGINIA 20191

ATTORNEY DOCKET NUMBER:	80505.264.US2	
NAME OF SUBMITTER:	: MICHELLE RHODES	
SIGNATURE:	/PMM/mr/	
DATE SIGNED:	07/25/2017	
	This document serves as an Oath/Declaration (37 CFR 1.63).	

Total Attachments: 2

source=80505-264-US2-PTO-20170724-Signed_Assignment-Declaration#page1.tif source=80505-264-US2-PTO-20170724-Signed_Assignment-Declaration#page2.tif

PATENT REEL: 043090 FRAME: 0024 504472131

COMBINED DECLARATION/ASSIGNMENT FOR UTILITY OR DESIGN APPLICATION

CONTACT WAFER	-,			
As a below named INVENTOR/ASSIGNOR, I hereby declare that:				
This declaration The attached application, or				
s directed to: United States application or PCT international application number				
filed on .				
The above-identified application was made or authorized to be made by me.				
believe that I am the original inventor or an original joint inventor of a claimed invention in the application.				
$hereby\ state\ that\ I\ have\ reviewed\ and\ understand\ the\ contents\ of\ the\ above-identified\ specification,\ including\ the\ claims.$				
acknowledge the duty to disclose information which is material to patentability as defined in 37 CFR § 1.56.				
WHEREAS, SAMTEC, Inc.				
(hereinafter referred to as "ASSIGNEE") having places of business at: <u>520 Park East Boulevard. New Albany, IN</u> <u>47151-1147</u> , is desirous of acquiring the entire right, title, and interest in, to, and under said invention and any Letters Patent that may be granted therefore in the United States and in any and all foreign countries;				
NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that in consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration, ASSIGNOR hereby sells, assigns, and transfers to ASSIGNEE the full and exclusive right, title, and interest to the said invention and all Letters Patent of the United States to be obtained therefore on said application or any continuation, division, renewal, substitute, or reissue thereof for the full term or terms for which the same may be granted; and all Letters Patent and applications therefore through the world, including all the rights accruing by virtue of the International Convention for the Protection of Industrial Property or other relevant International Treaties and Arrangements.				
ASSIGNOR hereby covenants that no assignment, sale, agreement, or encumbrance has been or will be made or ent <mark>ered int</mark> which would conflict with this assignment and sale;	O-			
ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention, and said Letters Patent as may be known and accessible to ASSIGNOR and will testify as to the same in any interference or litigation related thereto and will promptly execute and deliver to ASSIGNEE or its legal representative any and all papers, instruments, or affidavits required to apply for, obtain, maintain, and enforce said application, said invention, and said Letters Patent which may be necessary or desirable to carry out the purposes hereof.				
hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine o mprisonment of not more than five (5) years, or both.	r			
LEGAL NAME OF FIRST INVENTOR/ASSIGNOR				
nventor: Jonathan E. BUCK Date: 21 July 2017				
Signature: Howard LD DE				
LEGAL NAME OF SECOND INVENTOR/ASSIGNOR				
nventor: John A. MONGOLD Date:				
Signature:				

PATENT REEL: 043090 FRAME: 0025

COMBINED DECLARATION/ASSIGNMENT FOR UTILITY OR DESIGN APPLICATION

Title CONTACT WAFER			
As a below named INVENTOR/ASSIGNOR, I hereby declare that:			
This declaration The attached application, or			
is directed to: United States application or PCT international application number filed on	ani abananga nga		
The above-identified application was made or authorized to be made by me.			
I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.			
I hereby state that I have reviewed and understand the contents of the above-identified specification, includir claims.	g the		
I acknowledge the duty to disclose information which is material to patentability as defined in 37 CFR § 1.56.			
WHEREAS, SAMTEC, Inc. (hereinafter referred to as "ASSIGNEE") having places of business at: 520 Park East Boulevard, New Albany, I 47151-1147, is desirous of acquiring the entire right, title, and interest in, to, and under said invention and an Letters Patent that may be granted therefore in the United States and in any and all foreign countries;			
NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that in consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for good and valuable consideration, ASSIGNOR hereby sells, assigns, and transfers to ASSIGNEE the full and exciright, title, and interest to the said invention and all Letters Patent of the United States to be obtained therefor said application or any continuation, division, renewal, substitute, or reissue thereof for the full term or terms which the same may be granted; and all Letters Patent and applications therefore through the world, including the rights accruing by virtue of the International Convention for the Protection of Industrial Property or other relevant International Treaties and Arrangements.	usive e on for g all		
ASSIGNOR hereby covenants that no assignment, sale, agreement, or encumbrance has been or will be made of entered into which would conflict with this assignment and sale;	T		
ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention, and said Letters Patent as may be known and accessible to ASSIGNOR and will testify as to the same in any interference or litigation related thereto and will promptly execute and deliver to ASSIGNEE or its legal representative any and all papers, instruments, or affidavits required to apply for, obtain, maintain, and enforce said application, said invention, and said Letters Patent which may be necessary or desirable to carry out the purposes hereof.			
I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1 fine or imprisonment of not more than five (5) years, or both.	001 by		
LEGAL NAME OF FIRST INVENTOR/ASSIGNOR			
Inventor: Jonathan E. BUCK Date:	nani		
Signature:			
LEGAL NAME OF SECOND INVENTOR/ASSIGNOR			
Inventor: John A. MONGOZO Date: 7-24-17	_		
Signature:			

RECORDED: 07/25/2017

PATENT REEL: 043090 FRAME: 0026